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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant BRANDENBURG et al

Art Unit 2811

Attorney Docket Number DP-308286

Serial No. 10/643043

Filed August 18, 2003

Title PROCESS AND ELECTRONIC ASSEMBLY FOR REMOVING HEAT FROM A  
CIRCUIT DEVICE

STATEMENT ACCOMPANYING  
INFORMATION DISCLOSURE STATEMENT

Applicant(s) requests the Examiner to consider and make of record the reference(s) and/or information on attached PTO 1449.

**CHECK ONE: (A, B, or C.)**

☐ A. This statement is submitted within 1) three months after the filing date (even if after the first action); or 2) within three months of the date of entry of the national stage or 3) before the mailing date of a first Office Action. No fee or statement is required.

☒ B. This statement is submitted after the period specified in para. A, but before Final Office Action or Notice of Allowance or the close of prosecution.

**CHECK ONE: (1, 2, or 3)**

☒ 1. I hereby state that each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement; or

☐ 2. I hereby state that no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in § 1.56 (c) more than three months prior to the filing of the information disclosure statement.

☐ 3. Charge the fee set forth in § 1.17(p) to Delphi Technologies, Inc. Deposit Account No. 50-0831.

☐ C. This statement is submitted after a Final Office Action or Notice of Allowance or the close of prosecution, but before payment of the issue fee. Charge the fee set forth in § 1.17(p) to Delphi Technologies, Inc. Deposit Account No. 50-0831.

**CHECK ONE: (1 or 2)**

☐ 1. I hereby state that each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement; or

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**REMARKS UNDER 1.98 (a)(3)**

**Each of the cited references is relevant in that it was cited in a foreign counterpart application.**

Please consider the attached reference(s) which have come to the attention of Applicants since the last submission of an IDS. If any fee should be required, please charge the appropriate fee to Delphi Technologies, Inc. Deposit Account No. 50-0831.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "R. M. Sigler", is written over a horizontal line.

ROBERT M. SIGLER

Reg. No. 26505

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Enclosure: PTO 1449

## INFORMATION DISCLOSURE CITATION WITH DOCUMENT COPIES

Submitted by:

ROBERT M. SIGLER  
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10/643043Applicant  
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2811

## U.S. PATENT DOCUMENTS

Exam. Init.	Document Number	Date	Name	Class	Sub Class	Filing Date (if approp.)
	2001/026957	04-10-2001	Atwood et al.			
	6504723	07-01-2003	Fitzgerald et al.			
	2003/134454	17-07-2003	Houle			
	5396403	07-03-1995	Patel et al.			
	4034468	12-07-1977	Koopman			
	6307749	23-10-2001	Daanen et al.			
	6504242	07-01-2003	Deppisch et al.			

## FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Subclass	Translation Yes   No
0219424	07-03-2002	WO			Yes
0981159	23-02-2000	EP			No
19722357	19-11-1998	DE			No
61014096	22-01-1986	JP			Abstract Only

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

MASSALSKI T B: "Binary Alloy Phase Diagrams" BINARY ALLOY PHASE DIAGRAMS. AC-AU to FE-RH, OHIO, AMERICAN SOCIETY FOR METALS, US, vol. VOL. 1, 1986, Pages 268, 270-271, XP002177614 \*Page 270\*

SHIMIZU K et al.: "SOLDER JOINT RELIABILITY OF INDIUM-ALLOY INTERCONNECTION" JOURNAL OF ELECTRONIC MATERIALS, WARRENDALE, PA, US, vol. 24, no. 1, January 1995 (1995-01), Pages 39-45, XP000853947, \*column 9, paragraph 2-column 10\* \*Figures 13, 14\*

CHEN Y - C et al.: "A fluxless bonding technology using indium-silver multilayer composites" IEEE TRANSACTIONS ON COMPONENTS, PACKAGING, AND MANUFACTURING TECHNOLOGY, PART A IEEE USA, vol. 20, no. 1, March 1997 (1997-03), pages 46-51, XP002369584, ISSN: 1070-9886 \*figure 1\*

Copy of EP Search Report dated 20-Mar-2006

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Examiner

|Date Considered

**\*Examiner: Initial if reference considered whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.**

**Form PTO-FB-A820 (also PTO-1449) Patent & Trademark Office-US Dept. of Commerce**

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